

## **RB521CS30L**

# 100 mA low V<sub>F</sub> MEGA Schottky barrier rectifier

Rev. 1 — 24 January 2011

**Product data sheet** 

#### 1. Product profile

#### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882 leadless ultra small Surface-Mounted Device (SMD) plastic package.

#### 1.2 Features and benefits

■ Average forward current: I<sub>F(AV)</sub> ≤ 100 mA

Reverse voltage: V<sub>R</sub> ≤ 30 V

Low forward voltage: V<sub>F</sub> ≤ 350 mV

■ Low reverse current:  $I_R \le 10 \mu A$ 

AEC-Q101 qualified

Leadless ultra small SMD plastic package

#### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

#### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$I_{F(AV)}$	average forward current	square wave; $\delta$ = 0.5; f = 20 kHz				
		T <sub>amb</sub> ≤ 135 °C	<u>[1]</u> _	-	100	mA
		T <sub>sp</sub> ≤ 145 °C	-	-	100	mA
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V	-	2	10	μΑ
$V_R$	reverse voltage		-	-	30	V
$V_{F}$	forward voltage	I <sub>F</sub> = 10 mA	[2] _	280	350	mV

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.



<sup>[2]</sup> Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

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## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	[1]	. 54
2	anode	1 2	1 <del>    2</del> sym001
		Transparent top view	

<sup>[1]</sup> The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
RB521CS30L	-	leadless ultra small plastic package; 2 terminal; body 1.0 $\times$ 0.6 $\times$ 0.5 mm	SOD882

## 4. Marking

Table 4. Marking codes

Type number	Marking code
RB521CS30L	AR

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{R}$	reverse voltage		-	30	V
I <sub>F(AV)</sub> average forward current		square wave; $\delta$ = 0.5; f = 20 kHz			
		T <sub>amb</sub> ≤ 135 °C	<u>[1]</u> -	100	mA
		T <sub>sp</sub> ≤ 145 °C	-	100	mA
I <sub>FSM</sub>	non-repetitive peak forward current	half sine wave; $t_p \le 8.3 \text{ ms}$	[2] _	3	Α

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 Table 5.
 Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25  ^{\circ}C$	[4][3]	-	315	mW
			[4][1]	-	565	mW
T <sub>j</sub>	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-65	+150	°C
$T_{stg}$	storage temperature			-65	+150	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [2]  $T_i = 25$  °C prior to surge.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Reflow soldering is the only recommended soldering method.

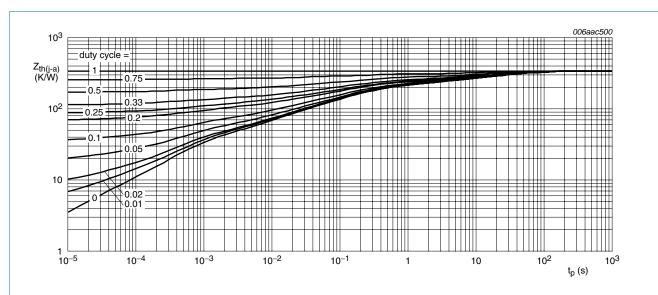
#### 6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from	in free air	[1][2]			
	junction to ambient		<u>[3]</u> _	-	395	K/W
			<u>[4]</u> _	-	220	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		<u>[5]</u> _	-	70	K/W

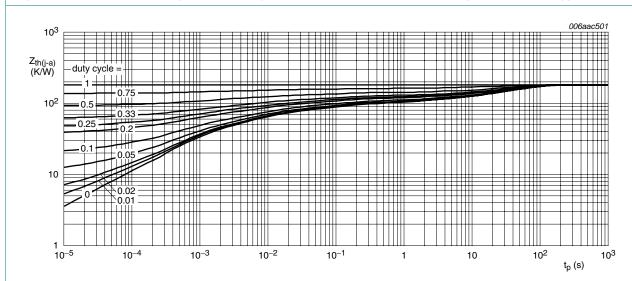
<sup>[1]</sup> For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [5] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

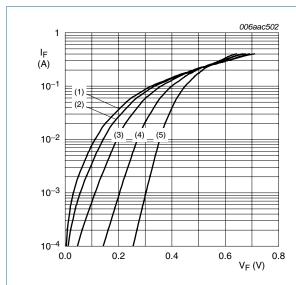
### 7. Characteristics

Table 7. Characteristics

T<sub>amb</sub> = 25 °C unless otherwise specified.

			Min	Тур	Max	Unit
$V_{F}$	forward voltage		[1]			
		$I_F = 0.1 \text{ mA}$	-	145	-	mV
		$I_F = 1 \text{ mA}$	-	210	-	mV
		$I_F = 10 \text{ mA}$	-	280	350	mV
		$I_F = 100 \text{ mA}$	-	405	-	mV
I <sub>R</sub>	reverse current	$V_R = 10 V$	-	2	10	μΑ
C <sub>d</sub>	diode capacitance	$V_R = 1 V$ ; $f = 1 MHz$	-	8	-	pF

[1] Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 





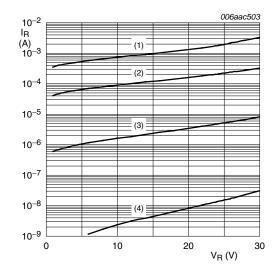
(2) 
$$T_i = 125 \, ^{\circ}\text{C}$$

(3) 
$$T_i = 85 \, ^{\circ}C$$

(4) 
$$T_j = 25 \,^{\circ}C$$

(5) 
$$T_i = -40 \, ^{\circ}\text{C}$$

Fig 3. Forward current as a function of forward voltage; typical values



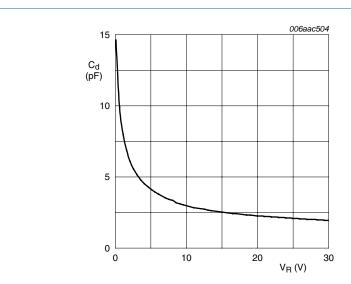
(1) T<sub>i</sub> = 125 °C

(2) 
$$T_j = 85 \, ^{\circ}C$$

(3) 
$$T_j = 25 \, ^{\circ}C$$

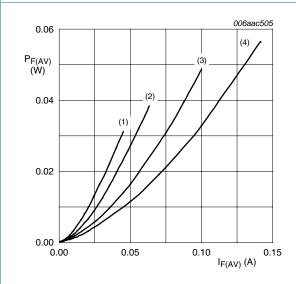
(4) 
$$T_j = -40 \, ^{\circ}C$$

Fig 4. Reverse current as a function of reverse voltage; typical values



f = 1 MHz;  $T_{amb} = 25 \, ^{\circ}\text{C}$ 

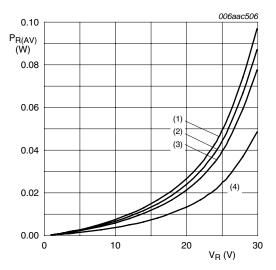
Fig 5. Diode capacitance as a function of reverse voltage; typical values



T<sub>i</sub> = 150 °C

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

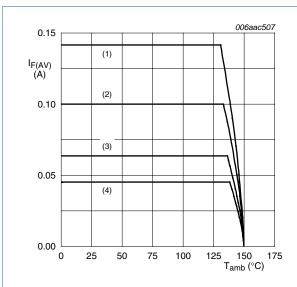
Fig 6. Average forward power dissipation as a function of average forward current; typical values



T<sub>j</sub> = 125 °C

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.9$ ; f = 20 kHz
- (3)  $\delta = 0.8$ ; f = 20 kHz
- (4)  $\delta = 0.5$ ; f = 20 kHz

Fig 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

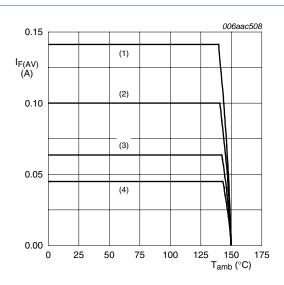
(1) 
$$\delta = 1$$
; DC

(2) 
$$\delta = 0.5$$
;  $f = 20 \text{ kHz}$ 

(3) 
$$\delta = 0.2$$
; f = 20 kHz

(4) 
$$\delta = 0.1$$
;  $f = 20 \text{ kHz}$ 

Fig 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

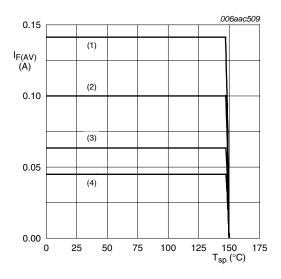
(1) 
$$\delta = 1$$
; DC

(2) 
$$\delta = 0.5$$
;  $f = 20 \text{ kHz}$ 

(3) 
$$\delta = 0.2$$
;  $f = 20 \text{ kHz}$ 

(4) 
$$\delta = 0.1$$
;  $f = 20 \text{ kHz}$ 

Fig 9. Average forward current as a function of ambient temperature; typical values



(1) 
$$\delta = 1$$
; DC

(3) 
$$\delta = 0.2$$
;  $f = 20 \text{ kHz}$ 

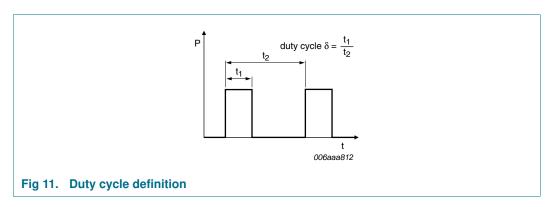
(4)  $\delta = 0.1$ ; f = 20 kHz

Fig 10. Average forward current as a function of solder point temperature; typical values

<sup>(2)</sup>  $\delta = 0.5$ ; f = 20 kHz

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#### 8. Test information



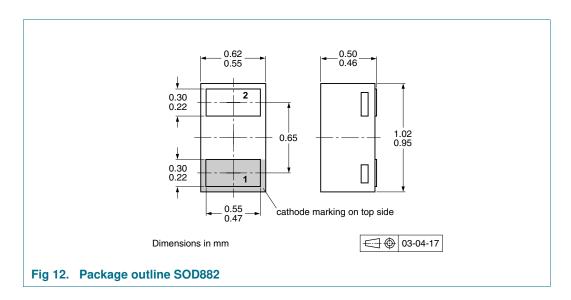
The current ratings for the typical waveforms as shown in <u>Figure 8</u>, <u>9</u> and <u>10</u> are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,

 $I_{RMS}$  =  $I_{F(AV)}$  at DC, and  $I_{RMS}$  =  $I_M \times \sqrt{\delta}$  with I<sub>RMS</sub> defined as RMS current.

#### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



## 10. Packing information

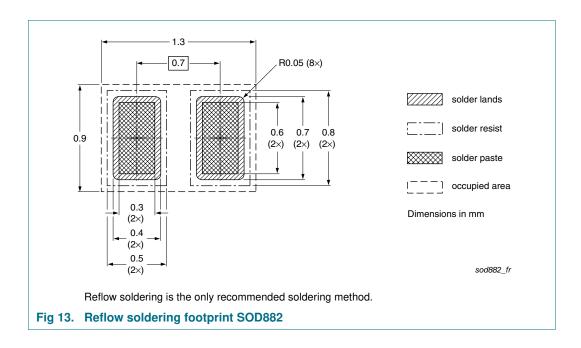
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity 10000
RB521CS30L	SOD882	2 mm pitch, 8 mm tape and reel	-315

<sup>[1]</sup> For further information and the availability of packing methods, see Section 14.

## 11. Soldering



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## 12. Revision history

#### Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
RB521CS30L v.1	20110124	Product data sheet	-	-

### 13. Legal information

#### 13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions"
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**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

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For sales office addresses, please send an email to: <a href="mailto:salesaddresses@nexperia.com">salesaddresses@nexperia.com</a>

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